



PATENT APPLICATION

Assistant Commissioner for Patents Box **Patent Application** Washington, D. C. 20231

Sir:

Enclosed herewith for filing is the following utility patent application:

ਰ Applicants: Padmapani C. Nallan, Guangxiang Jin, Ajay

Kumar

Title of application: METHOD OF PLASMA ETCHING OF HIGH-K
DIELECTRIC MATERIALS WITH HIGH
SELECTIVITY TO UNDERLYING LAYERS

Pages of specification: 14 (including 4 pages of claims and

1 page of abstract)

Sheets of drawing: <u>4</u>

Executed on: 3-6-02 Docket No.: 7017/ETCH/CORE

	PATENT APPLICATION FILING FEE CALCULA No. Filed Less Rate/Claim			TION <u>Fee</u>
Total Claims	34	-20	14 x \$18.00	\$252.00
Independent Claims	4	-3	1 x \$84.00	\$ 84.00
	Minimum Filing Fee			\$740.00
	Multiple Dependency Fee (if applicable - \$270.00)			\$
	50% Reduction for Small Entity (Independent Inventor, Non-profit Corporation, or Small Business Concern) - appropriate verified statement attached -			\$

TOTAL FILING FEE \$1076.00

Kindly charge the entire and/or any additional filing fee, as appropriate, to deposit account number $\underline{50-1074}$. To facilitate that charge, a duplicate copy of this letter is enclosed herewith.

Please direct all correspondence to:
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Also enclosed herewith for filing in connection with the enclosed application are:

Name of person mailing paper or fee